Physical Investigations of In$_2$O$_3$/Porous Silicon at Different Laser Wavelengths

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**ABSTRACT**

In this study, In$_2$O$_3$ thin films deposited on porous silicon using the pulsed laser deposition (PLD) method. The PSi substrate was prepared by photo electrochemical etching with the diode laser assistant. The impacts of various laser wavelengths on structural, spectroscopic, and performance characterizations were investigated. XRD revealed that the In$_2$O$_3$/PSi films have a polycrystalline cubic structure. The PL test showed measurements of two emission peaks related to In$_2$O$_3$ films (500, 463, 460 nm) and the PSi membrane (857, 852, 829 nm). The peaks at shorter wavelengths increased the energy gap from 2.4 eV to 2.69 eV. AFM results showed the surface roughness of the prepared samples were (3.78, 2.74, 2.3 nm), respectively and the root mean square (4.47, 3.26, 3.12 nm), respectively. FESEM images illustrated that the prepared samples had an average diameter size of (34.51, 25.55, 29.44 nm) with a cauliflower-like shape at 355 nm and rod-shaped particles for both 532 and 1064 nm. EDX tests were performed to figure out the elemental composition of In$_2$O$_3$/PSi the concentrations. The longer the laser wavelength, the higher the concentration of indium. The highest laser wavelength increased the transmission while decreasing the absorption.

**Keywords:** Indium Oxide, Nanostructure, Nano-films, Photo-electrochemical etching, Porous structure

1. INTRODUCTION

Indium oxide (In$_2$O$_3$) is a semiconductor material that exhibits excellent electrical, optical, and catalytic properties, making it a promising candidate for various applications, including biosensors [1, 2]. In$_2$O$_3$'s huge surface area, great biocompatibility, and strong conductivity have drawn a lot of interest in biosensor applications [3, 4].

1.1 Characteristics of In$_2$O$_3$

A good electrical conductor, In$_2$O$_3$ is a translucent, yellow-colored powder with a high electrical conductivity [5, 6]. Its great stability and durability make it a perfect choice for usage in difficult conditions [7, 8]. The huge surface area of In$_2$O$_3$ nanoparticles increases their sensitivity to biomolecules, making them a prime option for use in biosensors [9,10].

1.2 Advantages of In$_2$O$_3$

Compared to other materials used in biosensors, In$_2$O$_3$ offers a number of benefits, including great biocompatibility, strong conductivity, and a high surface area-to-volume ratio [11, 12]. Many techniques, including as co-precipitation, hydrothermal, and sol-gel, may be used to readily manufacture in2O3 [13, 14]. Additionally, In$_2$O$_3$ is extremely stable, making it a perfect substance for biosensors that need long-term stability [15, 16].

1.3 Applications of In$_2$O$_3$

Biosensors for the detection of several biomolecules, including as glucose, cholesterol, and DNA, frequently employ In$_2$O$_3$ [17, 18]. Excellent sensitivity, selectivity, and stability have been reported for In$_2$O$_3$-based biosensors, making them perfect for use in clinical and diagnostic applications [19, 20]. Applications for environmental monitoring and food safety have also employed In$_2$O$_3$-based biosensors [21, 22].

1.4 Utilization of In$_2$O$_3$ in Biosensors

Numerous biosensors, including electrochemical, optical, and field-effect transistor (FET) biosensors, have utilized In$_2$O$_3$ [23, 24]. Electrochemical biosensors based on In$_2$O$_3$ have been utilized to identify many compounds in blood samples, including glucose, cholesterol, and others [25, 26]. Optical biosensors based on In2O3 have been utilized to find DNA and protein biomarkers in clinical samples [29, 30]. Bacteria and viruses have been found using In$_2$O$_3$-based FET biosensors in environmental samples [31, 32].

1.5 Methods of Preparation

Indium oxide may be produced using a variety of techniques, such as chemical vapor deposition, sol-gel, and pulsed laser deposition (PLD). Among these, PLD has drawn a lot of interest because of its capacity to generate
uniform, high-quality thin films with fine control over the deposition settings.

Neodymium-doped yttrium aluminum garnet (Nd:YAG) laser is one of the frequently utilized laser sources for PLD. Utilizing laser pulses of a few nanosecond durations, the Nd:YAG laser PLD approach for indium oxide comprises ablation of an indium oxide target. A thin coating of indium oxide grows after the ablated material is put on a substrate in an oxygen-rich environment.

In order to regulate the structural and optical characteristics of the films, the deposition parameters may be changed, such as the laser fluence, oxygen pressure, and substrate temperature [33, 34].

For instance, a study showed that the indium oxide target’s crystalline quality and electrical conductivity were increased by using a high-temperature calcination procedure. [35, 36]. Overall, PLD employing the Nd:YAG laser and other laser sources offers a precise and effective way to create tunable indium oxide thin films, which may be applied in a variety of technical fields [37, 38].

In$_2$O$_3$ has good electrical, optical, and catalytic capabilities, making it a suitable material for biosensor applications. Excellent sensitivity, selectivity, and stability of In$_2$O$_3$-based biosensors make them the best choice for a variety of applications, including clinical and diagnostic, environmental monitoring, and food safety.

The use of In$_2$O$_3$ in a variety of biosensors, such as electrochemical, optical, and FET biosensors, emphasizes the material's potential for use in future biosensor technologies.

2. EXPERIMENTAL WORK

2.1 Preparation of Porous Silicon

Using photo electrochemical etching (PECE), n-type (111) porous silicon samples were created at room temperature. To get rid of any organic impurities, the silicon wafer was carefully cleaned before being chopped into little square pieces. It was inserted into the slot after being put in a Teflon cage with a circular slit at the bottom. This cell contains two electrodes.

The silicon wafer serves as the working electrode, while a counter electrode (usually a platinum wire) and a reference electrode are also included in the cell.

A piece of platinum (Pt) is immersed in an ethanol and hydrofluoric acid (HF) solution at the Teflon cell's top slot, acting as the cathode. The first, which has n-type silicon, functions as an anode and is attached to the bottom of the Teflon cell via an aluminum plate.

The 10% HF and 8% ethanol solution for the conduction of electrons delighted the silicon wafer. In order to construct a nan photonic silicon layer with a current density of 10 mA/cm$^2$ and an etching duration of 10 min, the illumination source used was a laser diode with a wavelength of 650 nm and a power density of 100 mW/cm$^2$ (China, Tongtool Inc.), DC power supply from 0 to 30V (China, Jiuyuan), Digital multimeter (China, Victor Inc., VC97) and 48% hydrofluoric acid electrolyte solution (Germen, Thomas Baker) and 99.9% ethanol (German, Honeywell Corporation). The laser was positioned 15 cm away from the cell, and platinum was placed at the center of the hole in Teflon's cell. The holes react with the silicon at the surface to create an oxide layer. This oxide layer is then etched away by the HF in the electrolyte solution, as a result of which holes in the silicon form.

The size and shape of the pores can be controlled by adjusting the etching conditions, such as the HF concentration, current density, and illumination intensity. The resulting porous silicon wafer is usually washed with ethanol of 99.9% and dried in an air dryer. It will be illuminated when blue light is shone on it.

2.2 Silicon Substrate

Approximately 1.5 cm x 1.5 cm-sized pieces of the silicon n-type (111) orientation single crystal silicon with (0.02 cm) resistivity and 500 m thickness single side polished wafer samples were split and thoroughly cleaned to remove any contaminants and fingerprints.

2.3 Quartz Substrate

The quartz samples were cut into pieces that were around 1.5 cm by 1.5 cm in size. The quartz material was chosen because it can withstand high temperatures without breaking or being damaged and because, in contrast to other materials, it can accommodate a wide variety of wavelengths.

2.4 Pulsed Laser Deposition (PLD)

Pulsed laser deposition (PLD) is a thin-film deposition technique that utilizes a high-energy pulsed laser to ablate material from a target and deposit it onto a substrate to form a thin film and it is a technique of physical vapor deposition (PVDPLD systems typically include a pulsed laser, vacuum pump, variac, thermometer, and a properly sealed chamber with two pipe-controlled airflow apertures (to avoid any gas leakage). One commonly used laser in PLD is the Nd:YAG (neodymium-doped yttrium aluminum garnet) laser. In the PLD process using an Nd:YAG laser, the laser beam is focused onto the surface of a target material (pressed indium oxide with a thickness of 1.5mm And diameter of 4mm). The target material absorbs the laser energy, causing it to vaporize and form a plasma plume that expands rapidly away from the target surface.

The plasma plume contains a high density of energetic particles, including neutral atoms, ions, and electrons, which are accelerated toward the substrate by the pressure generated by the plume expansion. The PLD parameters are presented in the Table 1. The substrate including pure silicon, porous silicon, and quartz, which is typically placed in close proximity to the target shown in Figure 1, is bombarded by the energetic particles in the
plasma plume, causing the deposition of a thin film. The deposition rate, thickness, and composition of the thin film can be controlled by adjusting the laser energy, pulse duration, and target-substrate distance.

### Table 1
The PLD method’s practical parameters

<table>
<thead>
<tr>
<th>Laser Parameters</th>
<th>Values</th>
</tr>
</thead>
<tbody>
<tr>
<td>Laser wavelengths</td>
<td>355 nm, 532 nm, 1064 nm</td>
</tr>
<tr>
<td>The energy of Pulsed</td>
<td>0.9 j</td>
</tr>
<tr>
<td>The duration of Pulsed</td>
<td>7 ns</td>
</tr>
<tr>
<td>Pulsed Frequency</td>
<td>3 Hz</td>
</tr>
<tr>
<td>Power supply</td>
<td>220 V</td>
</tr>
<tr>
<td>Repetition rate</td>
<td>300 Hz</td>
</tr>
<tr>
<td>Substrate temperature</td>
<td>Porous silicon 300°C</td>
</tr>
</tbody>
</table>

2.5 The Optical Characteristics Using XRD, AFM, FESEM, EDX, PL and UV

The porous silicon was put through several tests in order to find the most effective wavelength for the next step of work. The structural identity was verified by X-ray diffraction (XRD-6000 Shimadzu Co., Japan) of 1.54060 radiations generated by a copper cathode pipe. Field emission scanning electron microscopy (FESEM; Zeiss Co., Germany) was utilized to collect morphological data with high resolution, and photoluminescence (PL; Perkin Elmer Co., USA) was employed to assess the spectroscopic examination. Additionally, topographical structural properties were assessed using atomic force microscopy (AFM; TT2 Co., USA). Furthermore, energy-dispersive X-ray spectroscopy (EDX) was used to determine the elemental composition of a material, and finally, ultraviolet-visible spectroscopy (DR/UV-vis) was employed to measure the absorption and transmission of light in the ultraviolet and visible regions of the electromagnetic spectrum.

### Figure 1
PLD method diagram of In$_2$O$_3$ thin film at different laser wavelengths 355, 532, and 1064 nm.

### 3. RESULT AND DISCUSSION

#### 3.1 Crystalline Characteristics (XRD)

Figure 2 displays the PSi substrate with the XRD pattern. Without a diffraction signal at any value higher than $2 = 29^\circ$, the pattern was contained in the region of $2 = 27$–$29$. The XRD shows two peaks, one for the silicon at $2\theta = 27^\circ$ and the other for the PSi adhered with the silicon at $2\theta = 28.02^\circ$, related to (200) and (200) planes, respectively. The crystallite size of In$_2$O$_3$ can be calculated by using the Scherrer equation [39-41].

$$D = \frac{K\lambda}{\beta\cos\theta}$$  

where $D$ is the crystallite size, $K$ is Scherrer’s constant (usually taken to be 0.9), $\lambda$ is the wavelength of the X-rays used, $\beta$ (FWHM) is the full width at half maximum (in Radians) the diffraction peak, and $\theta$ is the Bragg angle (half of the diffraction angle) [42-44].

### Figure 2
The etching “Photo-electrochemical” assisted by the laser diode aid yielded an XRD pattern of a produced PSi substrate.

The X-Ray Diffraction patterns of In$_2$O$_3$ deposited on PSI at various laser wavelengths are shown in Figures 3 (a, b, and c). The position of 20 in the range of 10–70$^\circ$. The XRD patterns revealed that the In$_2$O$_3$ films were polycrystalline with a cubic structure [45-47]. All diffraction peaks were listed in Table 2 for each wavelength. The XRD patterns showed peaks in the range of 21 to 60.7, could be attributed to the deposition process of In$_2$O$_3$. The most noticeable crystallographic texture was seen in (222), with a high intensity peak in In$_2$O$_3$ at 355 nm, where the crystallite size was the smallest at 9.05 nm. The average crystallite size determined by Scherer’s equation increased as the laser wavelength became longer.
Table 2 Lists the In$_2$O$_3$/PSi XRD properties for various laser wavelengths

<table>
<thead>
<tr>
<th>Wavelength (nm)</th>
<th>Orientation (hkl)</th>
<th>(2θ) (degree)</th>
<th>FWHM (β) (degree)</th>
<th>The size of the Crystallite (D) (nm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>355</td>
<td>211</td>
<td>21.7</td>
<td>0.31</td>
<td>26.12</td>
</tr>
<tr>
<td></td>
<td>222</td>
<td>30.3</td>
<td>0.91</td>
<td>9.05</td>
</tr>
<tr>
<td></td>
<td>400</td>
<td>35.3</td>
<td>0.61</td>
<td>13.68</td>
</tr>
<tr>
<td></td>
<td>440</td>
<td>50.9</td>
<td>0.11</td>
<td>80.08</td>
</tr>
<tr>
<td></td>
<td>622</td>
<td>60.7</td>
<td>0.19</td>
<td>36.12</td>
</tr>
<tr>
<td>532</td>
<td>211</td>
<td>21</td>
<td>0.42</td>
<td>18.62</td>
</tr>
<tr>
<td></td>
<td>222</td>
<td>30.5</td>
<td>0.08</td>
<td>95.93</td>
</tr>
<tr>
<td></td>
<td>400</td>
<td>30.5</td>
<td>0.41</td>
<td>18.71</td>
</tr>
<tr>
<td></td>
<td>440</td>
<td>50.9</td>
<td>0.71</td>
<td>10.11</td>
</tr>
<tr>
<td></td>
<td>622</td>
<td>60.7</td>
<td>0.21</td>
<td>32.68</td>
</tr>
<tr>
<td>1064</td>
<td>211</td>
<td>21</td>
<td>0.11</td>
<td>71.10</td>
</tr>
<tr>
<td></td>
<td>222</td>
<td>30.1</td>
<td>0.18</td>
<td>42.67</td>
</tr>
<tr>
<td></td>
<td>400</td>
<td>35</td>
<td>0.59</td>
<td>12.85</td>
</tr>
<tr>
<td></td>
<td>440</td>
<td>50.6</td>
<td>0.15</td>
<td>47.94</td>
</tr>
<tr>
<td></td>
<td>611</td>
<td>58.4</td>
<td>0.55</td>
<td>12.62</td>
</tr>
<tr>
<td></td>
<td>622</td>
<td>60.6</td>
<td>0.19</td>
<td>36.14</td>
</tr>
</tbody>
</table>

3.2 Topographic Results AFM
The surface topography of grown In$_2$O$_3$ films was also examined using AFM at various wavelengths, as shown in Figures 4. At 355 nm, the surface was covered in sharp oval particles that formed the In$_2$O$_3$ layer. The film’s surface roughness was determined to be 3.78 nm, while the surface’s root mean square (RMS) was 4.47 nm.

3.3 Surface Morphology FESEM
Figures 5 display FESEM images of In$_2$O$_3$ films deposited at 355nm laser wavelengths, the average diameters of the In$_2$O$_3$ particles were 34.51 nm. The In$_2$O$_3$ film was grown at 355 nm in figure 8 D, and E, and the FESEM photos of the film reveal that it covered the PSi surface with uniform cauliflower-shaped particles with an average diameter of 34.51 nm that grew larger with the shorter wavelength.
Figure 5. FESEM images of grown In$_2$O$_3$ film at wavelength of 355 nm. D. Magnified 60,000X, E. Magnified 120,000X.

3.4 Energy Dispersive X-ray Spectroscopy (EDX)

Figure 6 illustrated the EDX analysis of the grown In$_2$O$_3$ thin film over Psi. The spectrum displays a prominent silicon peak along with smaller peaks for oxygen and indium, confirming the elemental composition. This analysis verifies the presence of oxygen, silicon, and indium under various laser wavelengths.

Figure 6. EDX spectrum at different laser wavelengths with 2000 mJ laser energy and 300°C substrate temperature. The X-axis represents counts and the Y-axis (KeV).

3.5 Spectroscopic Properties (Photoluminescence PL)

PL was performed at room temperature. For luminescence, a spectrometer (200-800 nm wavelengths) is used. The energy band gap could be calculated using this equation.

$$E_{\text{gap}} = \frac{hc}{\lambda} = 1240 / \lambda \text{ (nm)}$$

Where:

$E_{\text{gap}}$: the produced PSi substrate energy band.

$h$: Planck’s constant ($6.62 \times 10^{-34}$ J/Sec)

c: the speed of light ($3 \times 10^8$ m/sec)

$\lambda$: the wavelength peak of the prepared PSi substrate (847 nm).

Figures 7 show the PL spectra of Nano- In$_2$O$_3$ films prepared at 355 laser wavelengths. At 355 nm, the highest PL peak was observed at 500 nm, corresponding to a calculated energy gap of 2.4 eV. This peak was in the UV spectrum, whereas a modest emission peak in the IR spectrum was discovered, which is attributed to the presence of PSi in the sample. The UV peak suggests that the emission is likely due to defects or impurities in the In$_2$O$_3$ material rather than direct band-to-band recombination.
4. CONCLUSION

In$_2$O$_3$ thin films were deposited on a porous silicon substrate by the PLD method. Among the analytical techniques, each serves a specific purpose. The production was performed by the XRD test of In$_2$O$_3$ polycrystalline with a cubic structure. We investigated the elemental composition of the In$_2$O$_3$ film structures by EDX test. The morphology was tested by AFM and FESEM, which observed a roughness of 2.3 nm and a root mean square of 3.12 nm at 1064 nm, conforming to the best distribution of particles and making it the optimum wavelength.

REFERENCES


